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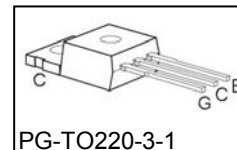
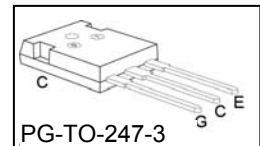
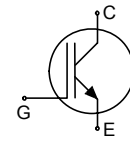
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HighSpeed 2-Technology

- **Designed for:**
 - SMPS
 - Lamp Ballast
 - ZVS-Converter
 - optimised for soft-switching / resonant topologies
- **2nd generation HighSpeed-Technology for 1200V applications offers:**
 - loss reduction in resonant circuits
 - temperature stable behavior
 - parallel switching capability
 - tight parameter distribution
 - E_{off} optimized for $I_C = 3A$
- Qualified according to JEDEC² for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	V_{CE}	I_C	E_{off}	T_j	Marking	Package
IGW03N120H2	1200V	3A	0.15mJ	150°C	G03H1202	PG-TO-247-3
IGP03N120H2	1200V	3A	0.15mJ	150°C	G03H1202	PG-TO-220-3-1

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
Triangular collector current	I_C	9.6 3.9	A
$T_C = 25^\circ\text{C}, f = 140\text{kHz}$			
$T_C = 100^\circ\text{C}, f = 140\text{kHz}$			
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	9.9	
Turn off safe operating area	-	9.9	
$V_{CE} \leq 1200\text{V}, T_j \leq 150^\circ\text{C}$			
Gate-emitter voltage	V_{GE}	± 20	V
Power dissipation	P_{tot}	62.5	W
$T_C = 25^\circ\text{C}$			
Operating junction and storage temperature	T_j, T_{stg}	-40...+150	°C
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	

² J-STD-020 and JESD-022

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		2.0	K/W
Thermal resistance, junction – ambient	R_{thJA}	PG-TO-220-3-1 PG-TO-247-3	62 40	

Electrical Characteristic, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=300\mu A$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=3A$ $T_j=25^\circ C$ $T_j=150^\circ C$ $V_{GE} = 10V, I_C=3A,$ $T_j=25^\circ C$	- - -	2.2 2.5 2.4	2.8 - -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=90\mu A, V_{CE}=V_{GE}$	2.1	3	3.9	
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$ $T_j=25^\circ C$ $T_j=150^\circ C$	- -	- -	20 80	μA
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE}=20V, I_C=3A$	-	2	-	S
Dynamic Characteristic						
Input capacitance	C_{iss}	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1MHz$	-	205	-	pF
Output capacitance	C_{oss}		-	24	-	
Reverse transfer capacitance	C_{riss}		-	7	-	
Gate charge	Q_{Gate}	$V_{CC}=960V, I_C=3A$ $V_{GE}=15V$	-	22	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E	PG-TO-220-3-1 PG-TO-247-3	- -	7 13	- -	nH

Switching Characteristic, Inductive Load, at $T_j=25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}$, $V_{CC}=800\text{V}$, $I_C=3\text{A}$, $V_{GE}=15\text{V}/0\text{V}$, $R_G=82\Omega$, $L_\sigma^{2)}=180\text{nH}$, $C_\sigma^{2)}=40\text{pF}$ Energy losses include "tail" and diode ³⁾ reverse recovery.	-	9.2	-	ns
Rise time	t_r		-	5.2	-	
Turn-off delay time	$t_{d(off)}$		-	281	-	
Fall time	t_f		-	29	-	
Turn-on energy	E_{on}		-	0.14	-	mJ
Turn-off energy	E_{off}		-	0.15	-	
Total switching energy	E_{ts}		-	0.29	-	

Switching Characteristic, Inductive Load, at $T_j=150^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j=150^\circ\text{C}$ $V_{CC}=800\text{V}$, $I_C=3\text{A}$, $V_{GE}=15\text{V}/0\text{V}$, $R_G=82\Omega$, $L_\sigma^{2)}=180\text{nH}$, $C_\sigma^{2)}=40\text{pF}$ Energy losses include "tail" and diode ³⁾ reverse recovery.	-	9.4	-	ns
Rise time	t_r		-	6.7	-	
Turn-off delay time	$t_{d(off)}$		-	340	-	
Fall time	t_f		-	63	-	
Turn-on energy	E_{on}		-	0.22	-	mJ
Turn-off energy	E_{off}		-	0.26	-	
Total switching energy	E_{ts}		-	0.48	-	

Switching Energy ZVT, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-off energy	E_{off}	$V_{CC}=800\text{V}$, $I_C=3\text{A}$, $V_{GE}=15\text{V}/0\text{V}$, $R_G=82\Omega$, $C_r^{2)}=4\text{nF}$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	-	0.05	-	mJ
			-	0.09	-	

²⁾ Leakage inductance L_σ and stray capacity C_σ due to dynamic test circuit in figure E

³⁾ Commutation diode from device IKP03N120H2

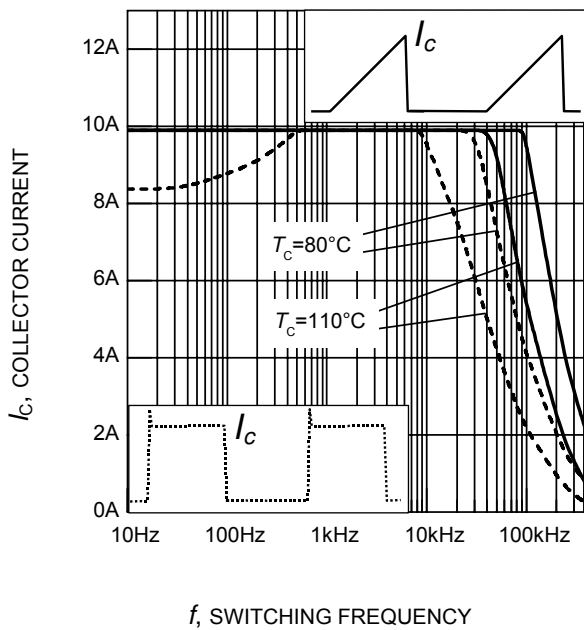


Figure 1. Collector current as a function of switching frequency
($T_j \leq 150^\circ\text{C}$, $D = 0.5$, $V_{CE} = 800\text{V}$, $V_{GE} = +15\text{V}/0\text{V}$, $R_G = 82\Omega$)

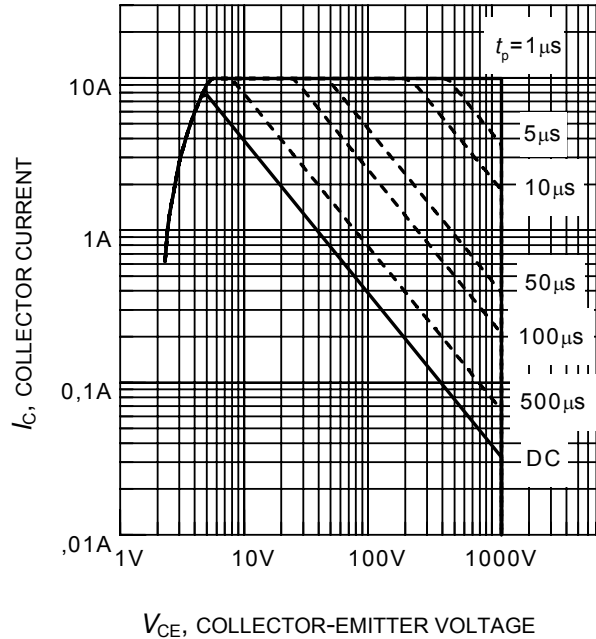


Figure 2. Safe operating area
($D = 0$, $T_C = 25^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$)

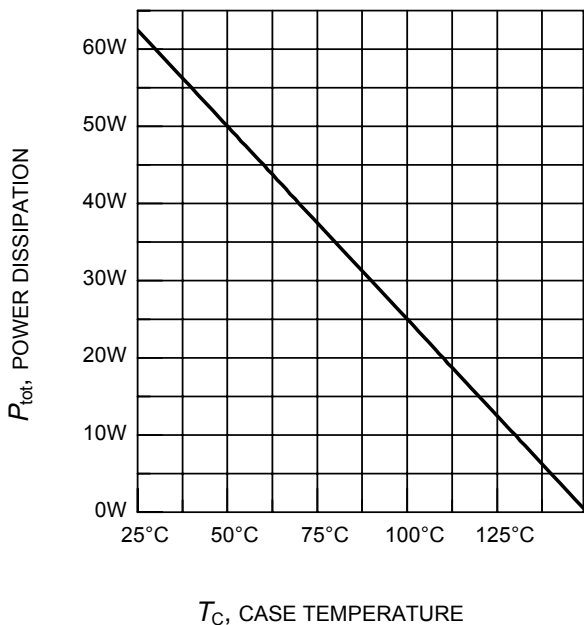


Figure 3. Power dissipation as a function of case temperature
($T_j \leq 150^\circ\text{C}$)

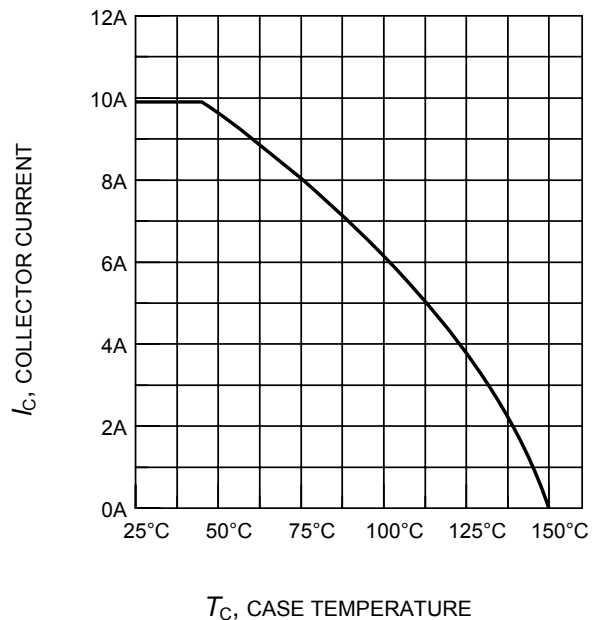
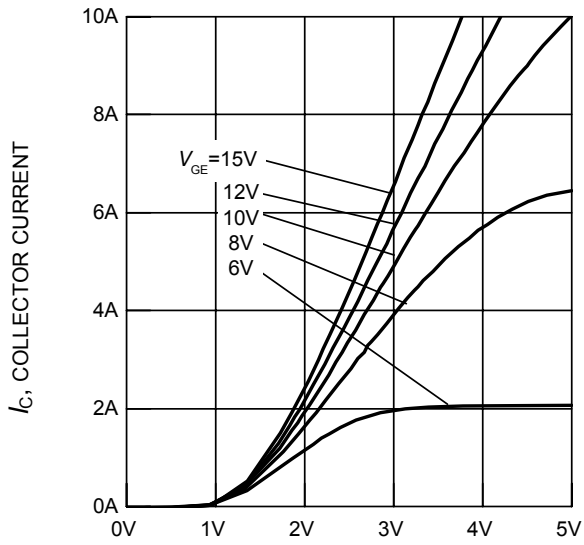
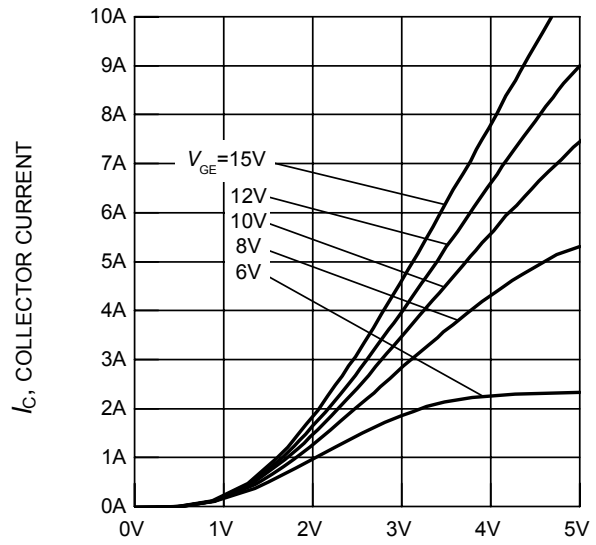


Figure 4. Collector current as a function of case temperature
($V_{GE} \leq 15\text{V}$, $T_j \leq 150^\circ\text{C}$)



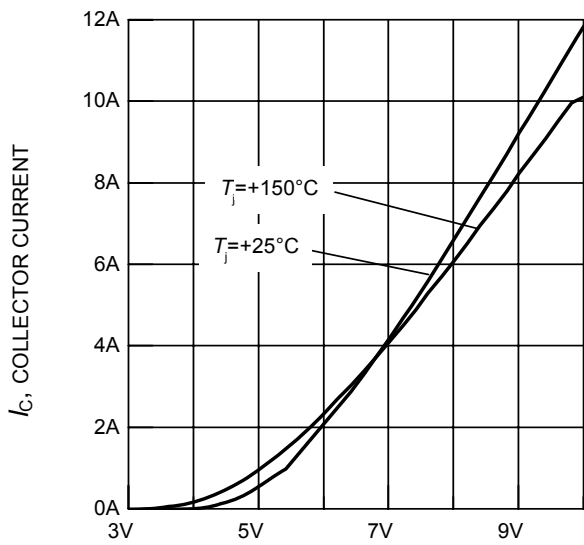
V_{CE} , COLLECTOR-EMITTER VOLTAGE

Figure 5. Typical output characteristics
($T_j = 25^\circ\text{C}$)



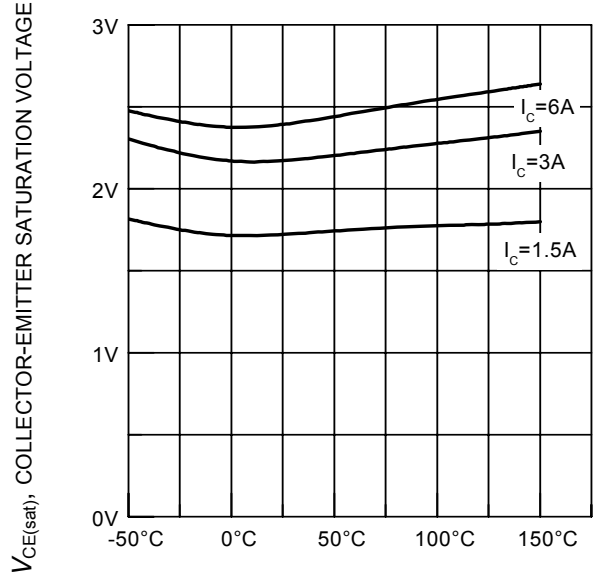
V_{CE} , COLLECTOR-EMITTER VOLTAGE

Figure 6. Typical output characteristics
($T_j = 150^\circ\text{C}$)



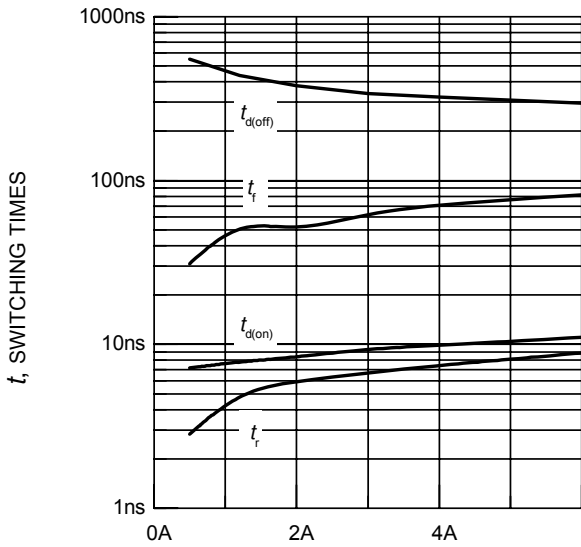
V_{GE} , GATE-EMITTER VOLTAGE

Figure 7. Typical transfer characteristics
($V_{CE} = 20\text{V}$)



T_j , JUNCTION TEMPERATURE

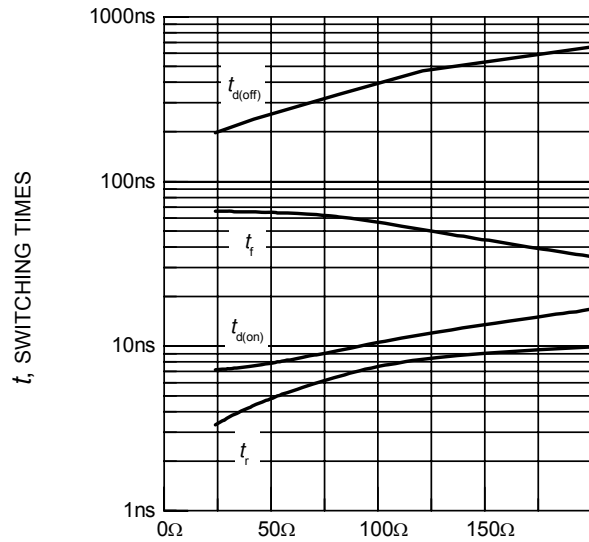
Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)



I_C , COLLECTOR CURRENT

Figure 9. Typical switching times as a function of collector current

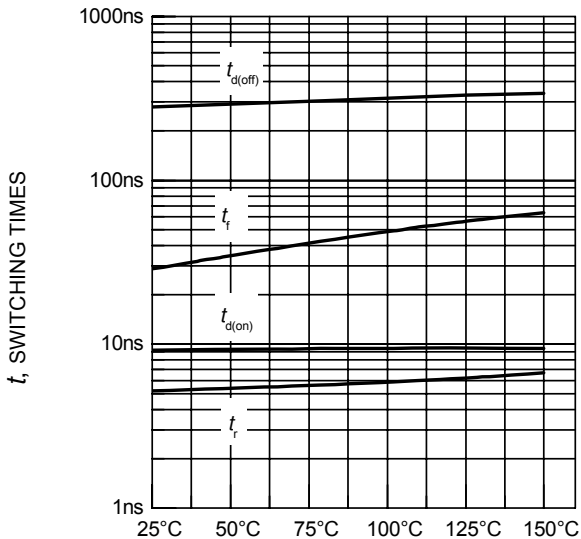
(inductive load, $T_j = 150^\circ\text{C}$,
 $V_{CE} = 800\text{V}$, $V_{GE} = +15\text{V}/0\text{V}$, $R_G = 82\Omega$,
dynamic test circuit in Fig.E)



R_G , GATE RESISTOR

Figure 10. Typical switching times as a function of gate resistor

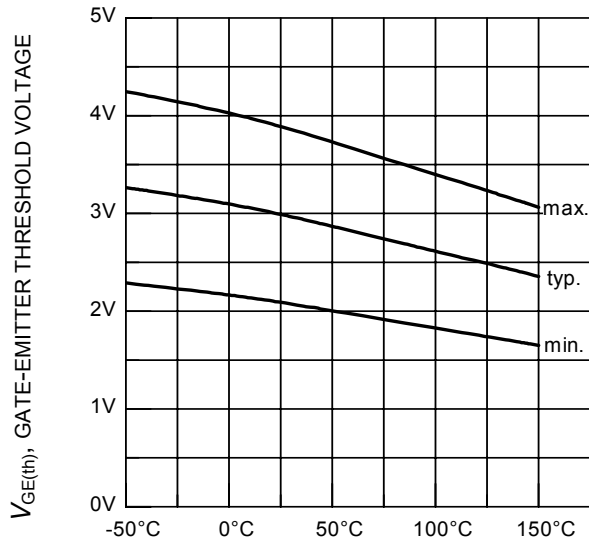
(inductive load, $T_j = 150^\circ\text{C}$,
 $V_{CE} = 800\text{V}$, $V_{GE} = +15\text{V}/0\text{V}$, $I_C = 3\text{A}$,
dynamic test circuit in Fig.E)



T_j , JUNCTION TEMPERATURE

Figure 11. Typical switching times as a function of junction temperature

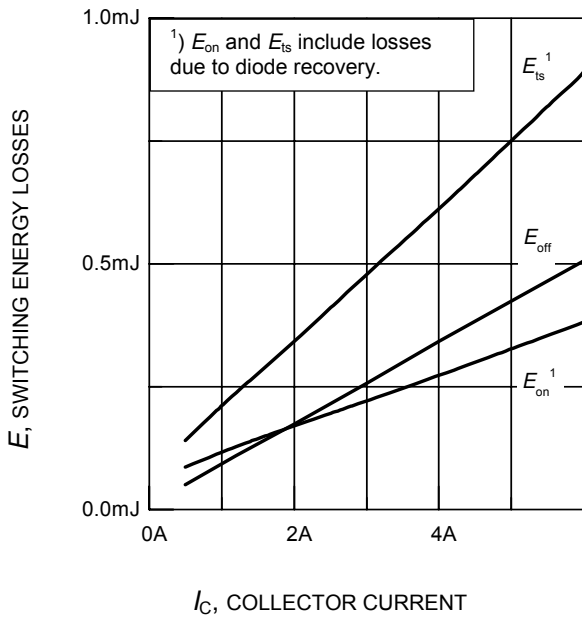
(inductive load, $V_{CE} = 800\text{V}$,
 $V_{GE} = +15\text{V}/0\text{V}$, $I_C = 3\text{A}$, $R_G = 82\Omega$,
dynamic test circuit in Fig.E)



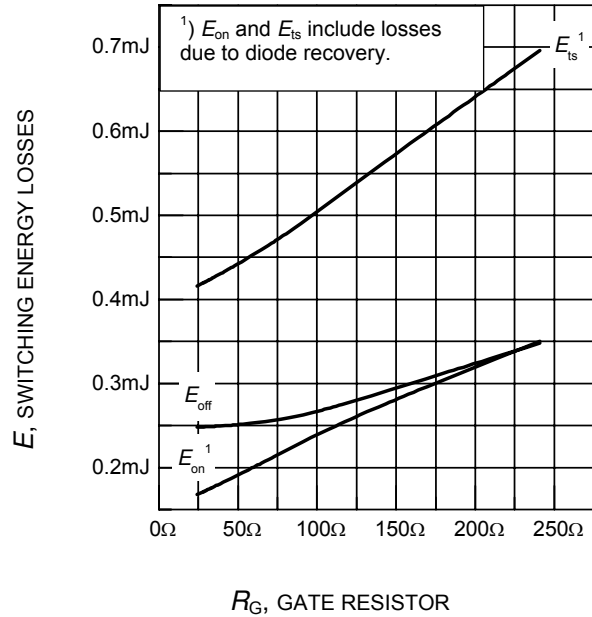
T_j , JUNCTION TEMPERATURE

Figure 12. Gate-emitter threshold voltage as a function of junction temperature

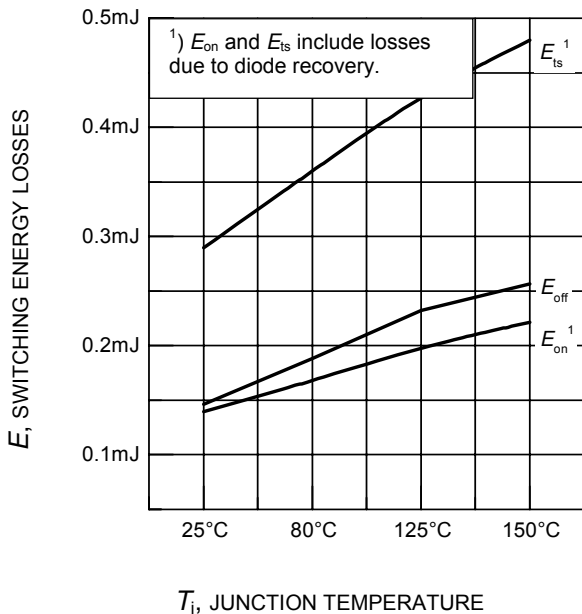
($I_C = 0.09\text{mA}$)



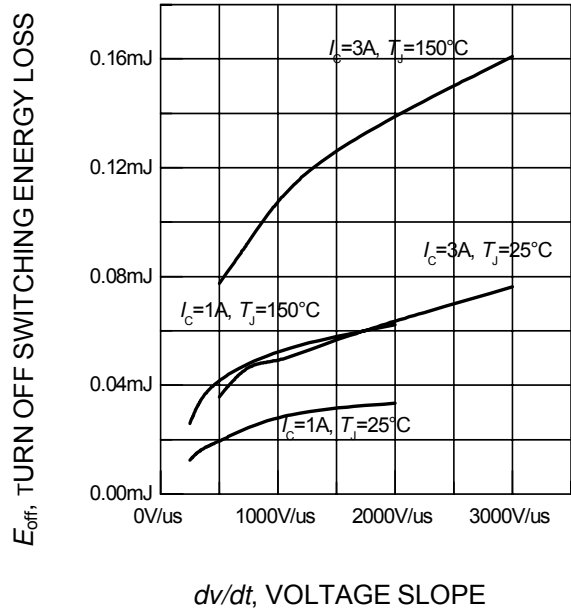
I_C , COLLECTOR CURRENT
Figure 13. Typical switching energy losses as a function of collector current
(inductive load, $T_j = 150^\circ\text{C}$, $V_{CE} = 800\text{V}$, $V_{GE} = +15\text{V}/0\text{V}$, $R_G = 82\Omega$, dynamic test circuit in Fig.E)



R_G , GATE RESISTOR
Figure 14. Typical switching energy losses as a function of gate resistor
(inductive load, $T_j = 150^\circ\text{C}$, $V_{CE} = 800\text{V}$, $V_{GE} = +15\text{V}/0\text{V}$, $I_C = 3\text{A}$, dynamic test circuit in Fig.E)



T_j , JUNCTION TEMPERATURE
Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, $V_{CE} = 800\text{V}$, $V_{GE} = +15\text{V}/0\text{V}$, $I_C = 3\text{A}$, $R_G = 82\Omega$, dynamic test circuit in Fig.E)



dv/dt , VOLTAGE SLOPE
Figure 16. Typical turn off switching energy loss for soft switching
(dynamic test circuit in Fig. E)

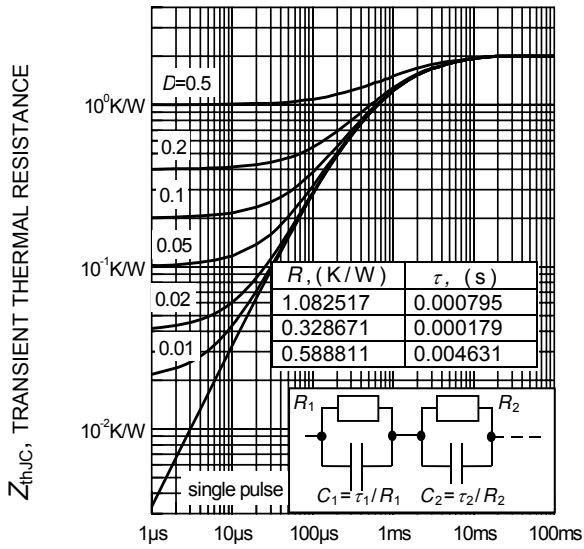


Figure 16. IGBT transient thermal resistance
($D = t_p / T$)

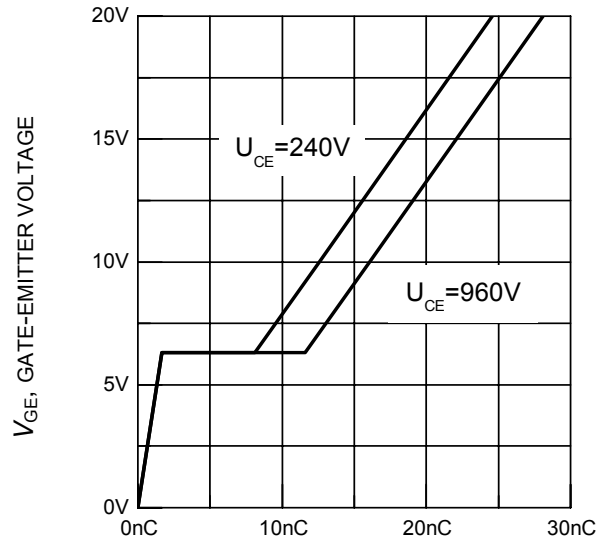


Figure 17. Typical gate charge
($I_C = 3A$)

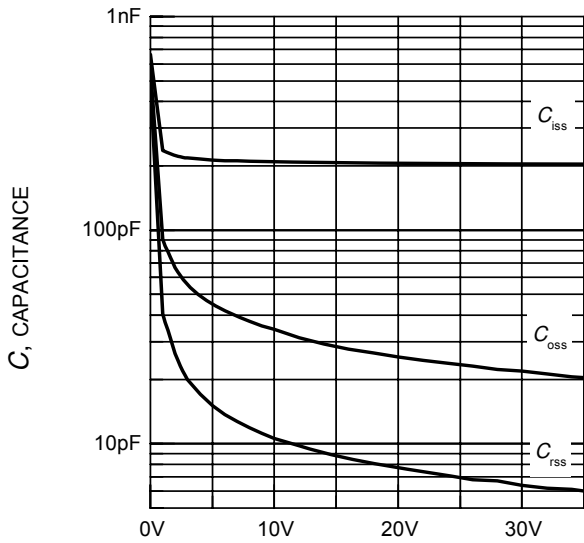


Figure 18. Typical capacitance as a function of collector-emitter voltage
($V_{GE} = 0V$, $f = 1MHz$)

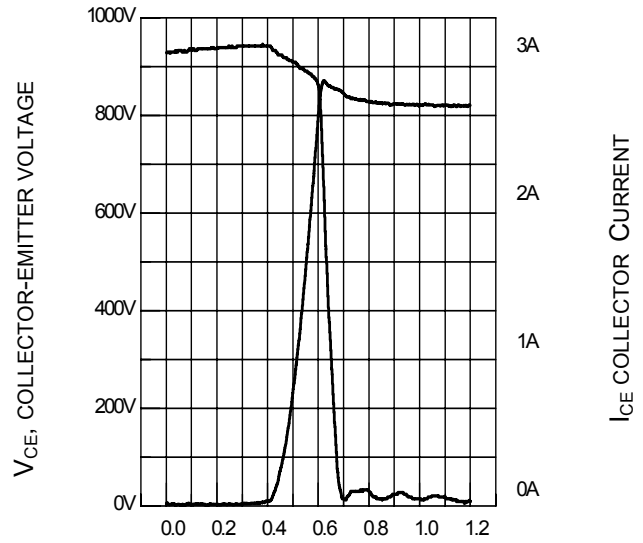


Figure 20. Typical turn off behavior, hard switching
($V_{GE} = 15/0V$, $R_G = 82\Omega$, $T_j = 150^\circ C$,
Dynamic test circuit in Figure E)

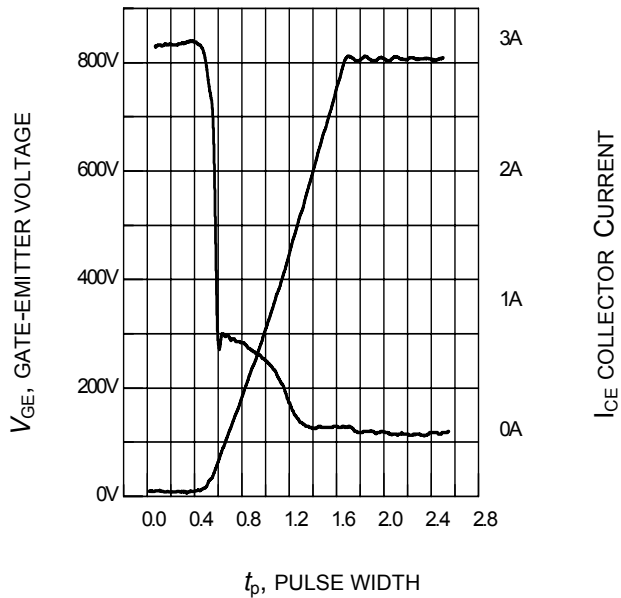
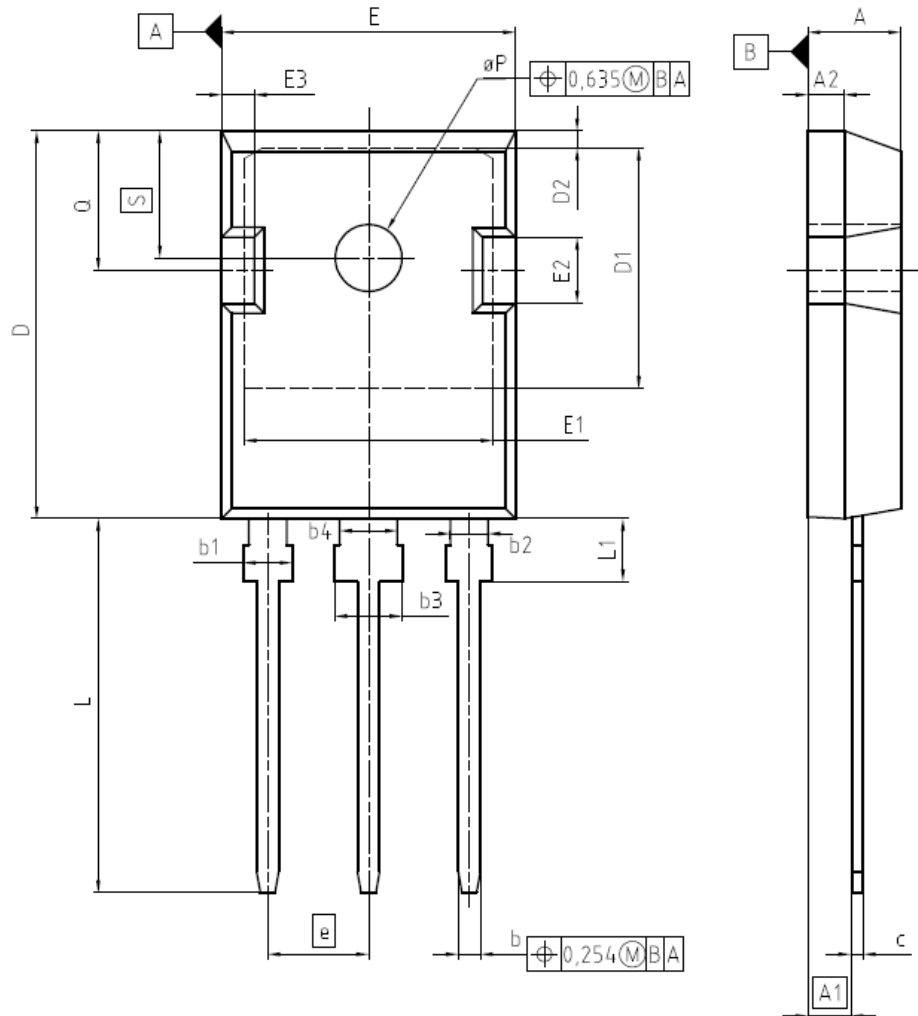


Figure 21. Typical turn off behavior, soft switching

($V_{GE}=15/0V$, $R_G=82\Omega$, $T_j = 150^\circ C$,
Dynamic test circuit in Figure E)

PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4,90	5,16	0,193	0,203
A1	2,27	2,53	0,089	0,099
A2	1,85	2,11	0,073	0,083
b	1,07	1,33	0,042	0,052
b1	1,90	2,41	0,075	0,095
b2	1,90	2,16	0,075	0,085
b3	2,87	3,38	0,113	0,133
b4	2,87	3,13	0,113	0,123
c	0,55	0,68	0,022	0,027
D	20,82	21,10	0,820	0,831
D1	16,25	17,65	0,640	0,695
D2	1,05	1,35	0,041	0,053
E	15,70	16,03	0,618	0,631
E1	13,10	14,15	0,516	0,557
E2	3,68	5,10	0,145	0,201
E3	1,68	2,60	0,066	0,102
e	5,44		0,214	
N	3		3	
L	19,80	20,31	0,780	0,799
L1	4,17	4,47	0,164	0,176
ϕP	3,50	3,70	0,138	0,146
Q	5,49	6,00	0,216	0,236
S	6,04	6,30	0,238	0,248

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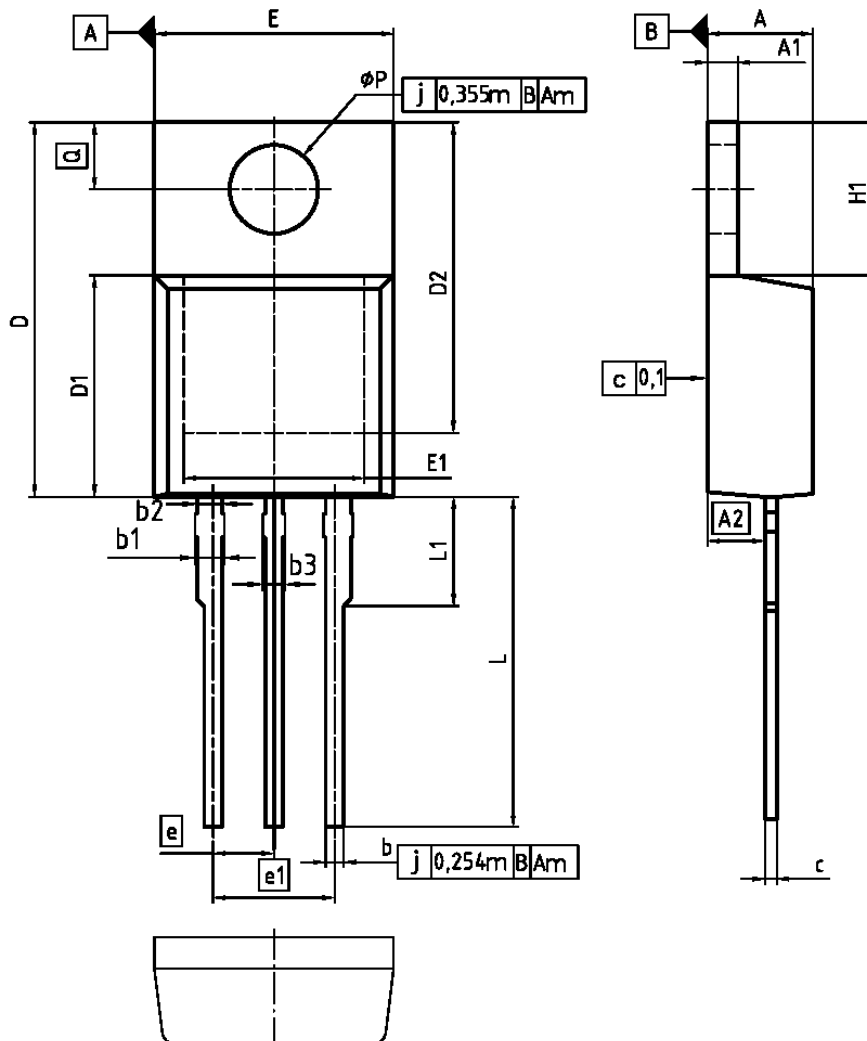
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PG-TO220-3-1



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	1.17	1.40	0.046	0.055
A2	2.15	2.72	0.085	0.107
b	0.65	0.86	0.026	0.034
b1	0.95	1.40	0.037	0.055
b2	0.95	1.15	0.037	0.045
b3	0.85	1.15	0.028	0.045
c	0.33	0.80	0.013	0.024
D	14.81	15.95	0.583	0.628
D1	8.51	9.45	0.335	0.372
D2	12.19	13.10	0.480	0.518
E	9.70	10.36	0.382	0.408
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H1	5.90	6.90	0.232	0.272
L	13.00	14.00	0.512	0.551
L1	-	4.80	-	0.189
øP	3.60	3.98	0.142	0.153
Q	2.60	3.00	0.102	0.118

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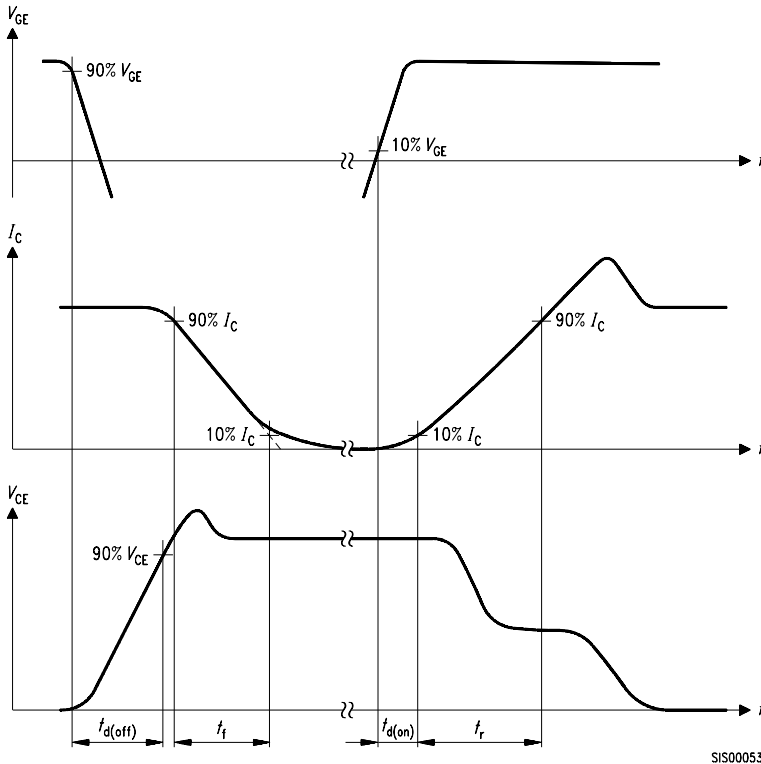


Figure A. Definition of switching times

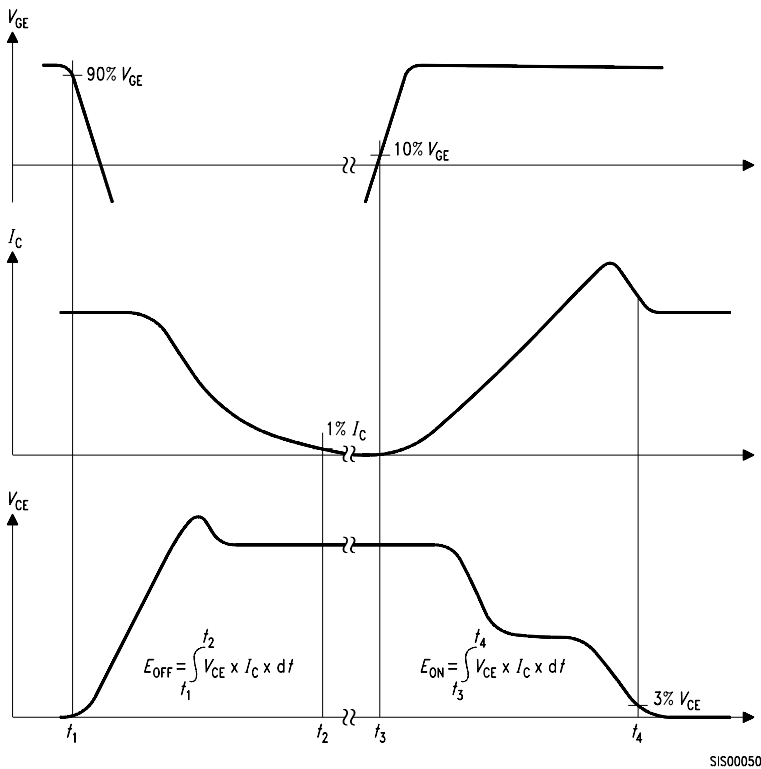


Figure B. Definition of switching losses

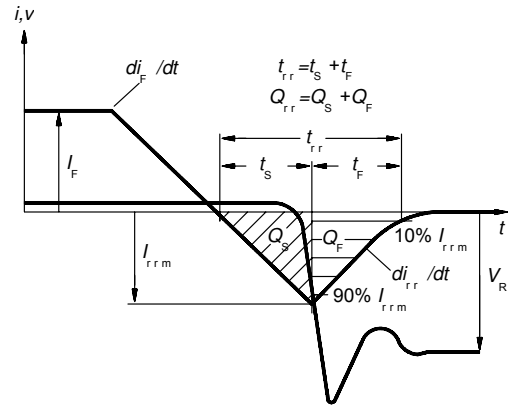


Figure C. Definition of diodes switching characteristics

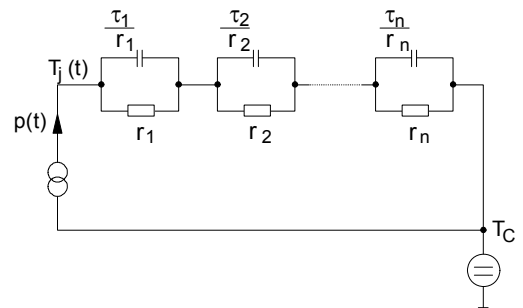


Figure D. Thermal equivalent circuit

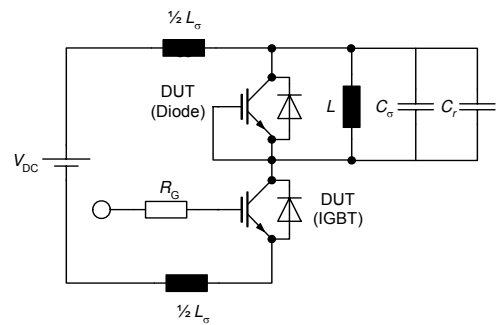


Figure E. Dynamic test circuit
Leakage inductance $L_\sigma = 180\text{nH}$,
Stray capacitor $C_\sigma = 40\text{pF}$,
Relief capacitor $C_r = 4\text{nF}$ (only for ZVT switching)

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